

L Number	Hits	Search Text	DB	Time stamp
1	0	206.ccls. and (polymer or polyimide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/05 13:34
2	6	((substrate with (bar or rail)) and ((polymer or polyimide) near (bar or rail)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/05 12:17
3	7	((carrier or tape) with (bar or rail)) and ((polymer or polyimide) near (bar or rail))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/05 12:25
4	1445	((carrier or tape or substrate) with (polymer or polyimide or polyamide)) and ((polymer or polyimide or polyamide) near (remove or removal or etch or eleminate or abrade or laser or cmp))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/05 12:31
5	1124	((carrier or tape or substrate) with (polymer or polyimide or polyamide)) and ((polymer or polyimide or polyamide) near (remove or removal or etch or eleminate or abrade or laser or cmp))) and(@ad<19990903)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/05 13:15
6	78	((carrier or tape or substrate) with (polymer or polyimide or polyamide)) and ((polymer or polyimide or polyamide) near (remove or removal or etch or eleminate or abrade or laser or cmp))) and(@ad<19990903)) and ((transport or transportation or move) with (substrate or carrier or film or tape) polyimide near (solder adj(resist or mask)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/05 13:13
8	47		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/05 13:14
9	32	(polyimide near (solder adj(resist or mask))) and(@ad<19990903)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/05 13:24
10	2	((index or alignment) adj hole\$2) with polyimide) same substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/05 13:30
11	1	("6179127").PN.	USPAT	2003/03/05 13:31
12	1	("6357591").PN.	USPAT	2003/03/05 13:31
13	1	("6357594").PN.	USPAT	2003/03/05 13:31
14	3128	206/\$.ccls. and (polymer or polyimide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/05 13:34
16	4	(206/\$.ccls. and (polymer or polyimide)) and ((remove or removal or etch or etching or cmp or laser or polish) near (polymer or polyimide))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/05 13:38
17	424	257/668.ccls. and polyimide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/05 13:38
18	7	(257/668.ccls. and polyimide) and ((remove or removal or etch or etching or cmp or laser or polish) near (polymer or polyimide))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/05 13:39